

WHAT IS CLAIMED IS:

1. A method for treating an object with a laser comprising the steps of:

emitting a laser beam from a laser;

expanding said laser beam in a first direction;

removing a portion of said laser beam through a mask, said portion including at least edges of said expanded laser beam extending in said first direction; and

condensing said laser beam in a second direction orthogonal to said first direction in order to form a line-shaped laser beam on an object.

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2. The method of claim 1 wherein the step of condensing said laser beam is done through a synthetic quartz lens.

3. The method of claim 1 wherein said laser is a pulse laser.

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4. The method of claim 1 wherein said laser is an excimer laser.

5. The method of claim 1 wherein said object treated with said laser has a semiconducting or insulating surface thereon.

6. A method for treating an object with a laser comprising the steps of:

emitting a rectangular-shaped laser beam from a laser;

expanding said laser beam in a first direction;

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removing a portion of said laser beam through a mask, said portion said portion including at least edges of said expanded laser beam extending in said first direction; and

condensing said laser beam in a second direction orthogonal to said first direction in order to form a line-shaped laser beam *on an* object.

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7. The method of claim 8 wherein the step of condensing said laser beam is done through a synthetic quartz lens.

8. The method of claim 6 wherein said laser is a pulse laser.

10 9. The method of claim 6 wherein said laser is an excimer laser.

10. The method of claim 6 wherein said object treated with said laser has a semiconducting or insulating surface thereon.

11. A method for treating an object with a laser comprising the steps of:

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emitting a laser beam from *a* laser;

expanding said laser beam in a first direction;

removing a portion of said laser beam through a mask, said portion including at least edges of said expanded laser beam extending in said first direction;

condensing said laser beam in a second direction orthogonal to said first direction in order to form a line-shaped laser beam *on an* object; and

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changing the relative location of said object with respect to said line-shaped laser beam so that said object is scanned with said line-shaped laser beam.

12. The method of claim 11 wherein the step of condensing said
5 laser beam is done through a synthetic quartz lens.

13. The method of claim 11 wherein said laser is a pulse laser.

14. The method of claim 11 wherein said laser is an excimer
laser.

15. The method of claim 11 wherein said object treated with said
10 laser has a semiconducting or insulating surface thereon.

16. The method of claim 11 wherein said object is scanned with
said line-shaped laser beam in said second direction orthogonal to the first
direction in which said laser beam is expanded.

*Att. Add. Add. 167
HHS*